

Title (en)

METHOD AND DEVICE FOR PRODUCING A SIC SOLID MATERIAL

Title (de)

VERFAHREN UND VORRICHTUNG ZUR HERSTELLUNG EINES SIC-FESTMATERIALS

Title (fr)

PROCÉDÉ ET DISPOSITIF DE PRODUCTION DE MATÉRIAU SOLIDE DE SIC

Publication

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Application

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Abstract (en)

[origin: WO2022123072A1] The present invention relates to a method for producing a preferably elongated SiC solid, in particular of polytype 3C. The method according to the invention preferably comprises at least the following steps: Introducing at least a first source gas into a process chamber, said first source gas comprising Si, introducing at least one second source gas into the process chamber, the second source gas comprising C, electrically energizing at least one separator element disposed in the process chamber to heat the separator element, setting a deposition rate of more than 200pm/h, wherein a pressure in the process chamber of more than 1 bar is generated by the introduction of the first source gas and/or the second source gas, and wherein the surface of the deposition element is heated to a temperature in the range between 1300°C and 1700°C.

IPC 8 full level

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